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TABLE OF CONTENTS
17th IEEE InterSociety Conference on
Thermal and Thermomechanical Phenomena in Electronic Systems

| | |
|--|------|
| Welcome to ITherm 2018 | iii |
| ITherm Committees | iv |
| Conference Schedule | vii |
| Keynotes | viii |
| Art-in-Science Exhibition | ix |
| ECTC/ITherm Joint Women’s Panel | x |
| Student Poster Session | x |
| Professional Development Courses | xi |
| Conference Technical Program | xii |
| Technology-Talk and Panel Sessions | xiii |
| Sponsors, Exhibitors, Partners | xiv |

Track: Emerging Technologies and Fundamentals

Session E-1: Fundamentals of Boiling and Condensation

Session Chairs: Amir Shooshtari (University of Maryland), Farah Singer (University of Maryland)

| | |
|---|-----------|
| Boiling Heat Transfer Performance of Three-dimensionally Ordered Microporous Copper with Modulated Pore Diameters (p122) | 1 |
| Quang Pham, Shiwei Zhang, Lin Cheng-Hui, Shuai Hao, Yoonjin Won (University of California, Irvine) | |
| Physics of Transition to Annular Flow in Microchannel Flow Boiling Process (p343) | 7 |
| Meisam Habibimatin, Abdolreza Fazeli, Saeed Moghaddam (University of Florida) | |
| Two-Level Copper Oxide Nanostructured Surfaces for Condensation Heat Transfer (p163) | 12 |
| Jonggyu Lee, Bowen Shao, Yoonjin Won (University of California, Irvine) | |

Session E-2: Flexible Electronics

Session Chairs: Banafsheh Barabadi (MIT), Mahsa Ebrahim (Villanova University), Aydin Nabovati (Tesla)

| | |
|--|-----------|
| Kapton RS Flexible Heaters - Design and Applications (p126) | 19 |
| Kalyan Rapolu, Shannon Dugan, Matthew Manelis, Jonathan Weldon, Richard Wessel (DuPont) | |
| Thermo-mechanical Deformation in Flexible-Board Assemblies during Reflow and Post-Assembly Usage (p322) | 26 |
| Pradeep Lall, Kartik Goyal (Auburn University); Ben Leever (US Air Force Research Labs); Jason Marsh (NextFlex) | |
| Highly Stretchable Metal Films on Polymer Substrates: Mechanics and Mechanisms (p210) | 32 |
| Yeasir Arafat, Rahul Panat, Indranath Dutta (Washington State University); Rahul Panat (Carnegie Mellon University) | |
| Novel Flexible Bioelectronics Device and Software Application for Prevention of Sudden Causes of Death (p331) | 37 |
| Pradeep Lall, Hao Zhang (Auburn University); Rahul Lall (Stanford University) | |

Session E-3: Thermal Transport in Nanotechnology

Session Chairs: Sukwon Choi (Pennsylvania State University), Yaguo Wang (University of Texas at Austin)

| | |
|---|-----------|
| Uncertainty Analysis of Near-Field Thermal Energy within Nanoparticle Packing (p195) | 46 |
| Anil Yuksel, Edward Yu, Michael Cullinan (University of Texas at Austin); Jayathi Murthy (UCLA) | |
| Thermal Transport Analysis of Heterostructured Nanowires with Metal-Semiconductor Interfaces (p198) | 51 |
| Nadjia Motley, Jaeho Lee (University of California, Irvine) | |
| Optical Pump-Probe Thermoreflectance Imaging for Anisotropic Heat Diffusion (p240) | 59 |
| Kazuaki Yazawa (Microsanj); Jesus Armando Leon Gil (CIMAV); Kerry Maize (Purdue University); Dustin Kendig (Microsanj); Ali Shakouri (Purdue University) | |
| Thermal Boundary Conductance Mapping at Metal-MoSe₂ Interface (p373) | 67 |
| David B. Brown (Georgia Institute of Technology); Xufan Li, Kai Xiao, David B. Geohegan (Oak Ridge National Laboratory); Satish Kumar (Georgia Institute of Technology) | |

Session E-4: Thermal Numerical Methods, Nano-to-Macro Scale

Session Chairs: Bladimir Ramos-Alvarado (Penn State University), Farah Singer (University of Maryland)

| | |
|--|-----------|
| Experimental and Numerical Investigation on Liquid Assisted Air Cooling Solution (p168) | 73 |
| Wenbin Tian, Devdatta Kulkarni, Ming Zhang, Yuehong Fan (Intel) | |
| <i>Morpho</i> Butterfly-Inspired Spectral Emissivity of Metallic Microstructures for Radiative Cooling (p209) | 78 |
| Anirudh Krishna, Jaeho Lee (University of California, Irvine) | |
| Interfacial Liquid Structuring at SiC-Water Interfaces and its Effects on Heat Transfer (p383) | 86 |
| C. Ulises Gonzalez-Valle, Bladimir Ramos-Alvarado (Pennsylvania State University) | |

Session E-5: Thermal Interface Materials and Phase Change Materials I

Session Chairs: Amy Marconnet (Purdue University), Leila Choobineh (SUNY Polytechnic Institute)

| | |
|--|------------|
| Phase Change Materials for Thermal Peak Management Applications with Specific Temperature Ranges (p211) | 92 |
| Jacob Maxa, Andrej Novikov, Mathias Nowotnick (University of Rostock); Matthias Heimann, Kay Jarchoff (Siemens AG) | |
| Chemical Modification of High Performance Metal-based Nanocomposite Thermal Interface Materials Toward Efficient Cooling in Electronic Systems (p275) | 102 |
| Cengiz Yegin, Nirup Nagabandi, Kevin Holder, Elisa Teipel (Incendium Technologies LLC); Mustafa Akbulut (Texas A&M University) | |
| Cooling Power and Thermal Buffering in Composite Heatsinks (p285) | 109 |
| Michael Deckard, Jonathan Felts, Patrick Shamberger (Texas A&M University) | |

Session E-6: Thermal Interface Materials and Phase Change Materials II

Session Chairs: Harish Ganapathy (Intel), Vibhash Jha (NXP Semiconductors)

| | |
|---|------------|
| Experimental Measurement of Corrosion Involving Inorganics (Salt Hydrates) Phase Change Materials (PCM) for Thermal Energy Storage (TES) Applications (p138) | 117 |
| Navin Kumar, Reynaldo Chavez Jr, Debjyoti Banerjee (Texas A&M University) | |
| Design Architectures for Compliant High Temperature Thermal Interface Materials (p147) | 126 |
| Mei-Chien Lu (Monte Rosa Technology) | |

| | |
|--|------------|
| Influence of Structure and Wettability of Porous Silver Surfaces on Enhancing Phase Change Heat Transfer (p159) | 134 |
| Gideon Gouws, Ben Sherson, Arwin Sinnathambi, Roshni Babu, Ciaran Moore (Victoria University of Wellington) | |

| | |
|---|------------|
| Numerical and Experimental Investigation of Vertically Aligned Carbon Nanotube-Phase Change Material Composites for Thermal Management of Electronics (p400) | 141 |
| Makita Phillips, Craig Green, Baratunde Cola (Carbice Corporation) | |

Session E-7: Convection in Channels and Jets

Session Chairs: Bladimir Ramos-Alvarado (Penn State University);
Farah Singer, Amir Shooshtari (University of Maryland)

| | |
|--|------------|
| A Heat Spreading Model for Double-Sided, Cross-Flow, Manifold-Microchannel Heat Exchangers (p228) | 147 |
| Raphael Mandel, Martinus Arie, Amir Shooshtari, Michael Ohadi (University of Maryland) | |

| | |
|--|------------|
| A Header Design Method for Target Flow Distribution among Parallel Channels Based on Topology Optimization (p111) | 156 |
| Shi Zeng, Poh Seng Lee (National University of Singapore) | |

| | |
|---|------------|
| Impact of Orifice Size over Mechanical, Flow and Thermal Performances of Synthetic Jets (p120) | 164 |
| Onuralp Isil, Bogac Yucesan, Mehmet Arik (Ozyegin University) | |

| | |
|---|------------|
| Experimental Characterization of a Microchannel Heat Sink Made by Additive Manufacturing (p135) | 171 |
| Ivel Collins, Justin Weibel, Liang Pan, Suresh Garimella (Purdue University) | |

Session E-9: Thermal Experimental Methods, Nano-to-Macro Scale I

Session Chairs: Amy Marconnet (Purdue University), Patrick Shamberger (Texas A&M University)

| | |
|---|------------|
| Estimation of Measurement Uncertainties for Thermal Conductivity of Nanofluids using Transient Plane Source (TPS) Technique (p137) | 178 |
| Binjian Ma, Navin Kumar, Aditya Kuchibhotla, Debjyoti Banerjee (Texas A&M University) | |

| | |
|-------------------------|------------|
| (paper withdrawn) | 187 |
|-------------------------|------------|

| | |
|--|------------|
| CTE-Matched Cantilevers for Improved Heated Atomic Force Microscopy and Passive-mode Scanning Thermal Microscopy (p243) | 191 |
| Darin Sharar (General Technical Services, LLC), Adam Wilson (National Academy of Sciences National Research Council) | |

Session E-10: Thermal Experimental Methods, Nano-to-Macro Scale II

Session Chairs: Amy Marconnet (Purdue University), Patrick Shamberger (Texas A&M University)

| | |
|--|------------|
| Measurement and Modeling of Heat Conduction in MEMS Nanostructures (p174) | 196 |
| Marcin Janicki, Piotr Pietrzak, Piotr Zajac, Grzegorz Jablonski (Lodz University of Technology); Pawel Janus (Institute of Electron Technology) | |

| | |
|---|------------|
| Temperature and Stress Metrology of Ultra-Wide Bandgap β-Ga₂O₃ Thin Films (p289) | 202 |
| Bikramjit Chatterjee, Sukwon Choi (Pennsylvania State University); Jacob Leach (Kyma Technologies); Sarit Dhar (Auburn University) | |

| | |
|--|------------|
| Improving the Transient Thermal Characterization of GaN HEMTs (p307) | 208 |
| Georges Pavlidis, Dustin Kendig, Luke Yates, Samuel Graham (Georgia Institute of Technology) | |

| | |
|--|------------|
| Investigation of Elastic Modulus and Thermal Conductivity of Rough Silicon Nanowires (p391) | 214 |
| Kenny Huynh, Majed Madani, Jaeho Lee (University of California, Irvine) | |

Session E-11: Emerging Materials and Thermal Phenomena I

Session Chairs: Banafsheh Barabadi (MIT), Taravat Khadivi (Qualcomm)

| | |
|--|------------|
| First Demonstration of a Bendiang-Mode Elastocaloric Cooling 'Loop' (p116) | 218 |
| Darin Sharar, Brendan Hanrahan (U.S. Army Research Laboratory); Joshua Radice, Ronald Warzoha (United States Naval Academy); Benjamin Chang (University of Maryland) | |
| Temperature-Dependent Thermoelectric Properties of Electrodeposited Antimony Telluride Films upon Thermal Annealing (p206) | 227 |
| Ziqi Yu, Laia Ferrer-Argemi, Jaeho Lee (University of California, Irvine) | |
| Thermal Conductivity of Electrically Conductive Highly Boron Doped Diamond and its Applications at High Frequencies (p213) | 235 |
| Gruffudd Williams (Element Six Technologies); Julian Anaya Calvo (J. Anaya Calvo Scientific Consultancy); Firooz Faili, Joe Dodson, Thomas Obeloer, Daniel Twitchen (Element Six Technologies) | |
| Temperature-Dependent Adhesion Mechanisms of Metal and Insulator Probe-Sample Contact Pairs (p242) | 240 |
| Adam Wilson (National Academy of Sciences National Research Council), Darin Sharar (General Technical Services, LLC) | |

Session E-12: Emerging Materials and Thermal Phenomena II

Session Chairs: Sukwon Choi (Pennsylvania State University), Yaguo Wang (UT Austin), and Banafsheh Barabadi (MIT)

| | |
|---|------------|
| Experimental Measurement of the Effect of Particle Concentration on the Specific Heat Capacity of Silica Nanofluids (p143) | 246 |
| Binjian Ma, Navin Kumar, Aditya Kuchibhotla, Debjyoti Banerjee (Texas A&M University) | |
| Thermal Conductivity of Graphite Microlattices (p201) | 252 |
| Shiva Farzinazar, Zongqing Ren, Jaeho Lee (University of California, Irvine) | |
| Non-Invasive Thermal Resistance Measurement for GaN Wafer Process Control and Optimization (p249) | 256 |
| Chao Yuan, James Pomeroy, Martin Kuball (University of Bristol) | |
| LED Characterization within the Delphi4LED Project (p393) | 262 |
| Gabor Farkas, Lajos Gaal, Marton Bein, Andras Poppe, Sandor Ress, Marta Rencz (Mentor) | |

TRACK: THERMAL I – COMPONENT LEVEL

Session TI-1A: 3D Packaging / 3D Embedded Cooling I

Session Chairs: Bidzina Kekelia (NREL), Timothy Chainer (IBM Research)

| | |
|---|------------|
| Sim2Cool: A Two-Phase Cooling System Simulator and Design Tool (p268) | 271 |
| Pritish Parida, Mark Schultz, Timothy Chainer (IBM Research) | |
| Two-Phase Flow Characteristics in Radial Expanding Channels with Embedded Pin Fins (p270) | 281 |
| Mark Schultz (IBM Research); Michael Gaynes (Universal Instruments); Pritish Parida (IBM Research); Fanghao Yang (Princeton Plasma Physics Lab); Gerard McVicker, Ozgur Ozsun, Timothy Chainer (IBM Research) | |
| Embedded Fluid Cooling of Close-packed Via Arrays in Glass (p319) | 288 |
| Michael Fish, Bradley Martinis, Patrick McCluskey, Avram Bar-Cohen (University of Maryland) | |

Session TI-1B: Vapor Chambers and Heat Pipes

Session Chairs: Sukhvinder Kang (Boyd), Kamal Sikka (IBM)

| | |
|--|------------|
| 2D Design of Channels in Vapor Chamber with Topological Optimization (p182) | 296 |
| Hao You, Wen Wang (Shanghai Jiao Tong University) | |
| Performance Evaluation of Bent Heat Pipes (p260) | 302 |
| Agile Johns, Fred Barez, Ernie Thurlow, Younes Shabany (San Jose State University) | |

| | |
|--|------------|
| Characterization of a Heat Sink with Embedded Heat Pipe with Variable Heat Dissipating Source Placement for Power Electronics Applications (p384) | 311 |
| Neda Mansouri, Cliff Weasner, Ahmed Zaghlol (Mersen Canada Toronto Inc) | |

Session TI-2: 3D Packaging / 3D Embedded Cooling II

Session Chairs: Timothy Chainer (IBM Research), Bidzina Kekelia (NREL)

| | |
|---|------------|
| Thermal Performance Comparison of Advanced 3D Packaging Concepts for Logic and Memory Integration in Mobile Cooling Conditions (p139) | 318 |
| Herman Oprins, Vladimir Cherman, Eric Beyne (IMEC) | |
| Methodology for 3D Package Selection using Thermal Violation Region Graph (p308) | 325 |
| Yunhyeok Im, Kyoung Min Lee, Heeseok Lee, Junho Huh (Samsung Electronics) | |
| Dual-Side Heat Removal by Silicon Cold Plate and Interposer with Embedded Fluid Channels (p121) | 331 |
| Thomas Brunschwiler (IBM Research Zurich); Wolfram Steller, Hermann Oppermann, Jessica Kleff (Fraunhofer); Stephen Robertson (Optocap Ltd); Raul Mrossko, Juergen Keller (AMIC); Gerd Schlottig (IBM Research Zurich) | |
| Cooling of Miniature Electronic Systems Using Diamond Circuit Boards (p158) | 340 |
| Nicholas Apollo, Arman Ahnood, Hualin Zhan, Kumar Ganesan, Alan Smith, Steven Praver, David Garrett (University of Melbourne) | |

Session TI-3: Single/Multi Chip Module (MCM) and System in Package (SIP) I

Session Chairs: Stephanie Allard (IBM), Sami Alkharabsheh (Ford)

| | |
|--|------------|
| Thermal Co-Design of Exascale Computing System in Packages (SiPs) (p127) | 345 |
| Koosha Nassiri Nazif (Stanford University); Niru Kumari, Sarah Silverthorn (Hewlett Packard Enterprise) | |
| Novel Programmable Package-level Thermal Evaluation System (p380) | 354 |
| Suresh Parameswaran, Gamal Refai-Ahmed, Suresh Ramalingam, Boon Ang (Xilinx) | |
| Warpage Management for Fan-Out Packaging Moving from Wafer Level to Panel Level (p146) | 360 |
| Mei-Chien Lu (Monte Rosa Technology) | |
| Hybridizing Nature-inspired Algorithms to Derive Accurate Surrogate Thermal Model: Genetic Algorithm and Particle Swarm Optimization (p199) | 368 |
| Eric Monier-Vinard, Olivier Daniel, Valentin Bissuel, Brice Rogié, Minh-Nhat Nguyen (Thales Corporate Engineering); Brice Rogié, Minh-Nhat Nguyen, Najib Laraqi (Université Paris Ouest); Ismaël Aliouat (Université Paris-Saclay) | |

Session TI-4: Single/Multi Chip Module (MCM) and System in Package (SIP) II

Session Chairs: Sami Alkharabsheh (Ford), Stephanie Allard (IBM)

| | |
|--|------------|
| Design and Parametric Study of Microfluidic Cooling Manifold for 2.5D-SiCs with Dielectric Coolant (p234) | 379 |
| Yuanchen Hu, Thomas Sarvey, Muhannad Bakir, Yogendra Joshi (Georgia Institute of Technology) | |
| An Innovative Heterogeneous SoC Thermal Model for Smartphone System (p239) | 384 |
| Sheng-Liang Kuo, Chi-Wen Pan, Pei-Yu Huang, Chien-Tse Fang, Shin-Yu Hsiau, Tai-Yu Chen (MediaTek) | |
| Analysis of Thermal Characteristics of Gallium Oxide Field-Effect-Transistors (p256) | 392 |
| Jialuo Chen, Satish Kumar (Georgia Institute of Technology); Zhanbo Xia, Siddharth Rajan (Ohio State University) | |
| Model-Based Comparison of Thermo-Hydraulic Performance of Various Cooling Methods for Power Electronics of Electric Vehicles (p273) | 398 |
| Jasper Nonneman, Ilya TJollyn, Nils Clarie, Peter Sergeant, Michel De Paepe (Ghent University and Flanders Make); Sam Weckx (Flanders Make) | |

Session TI-5: Hot Spot Cooling and Jet Impingement I

Session Chairs: Nicholas Haehn (Intel), Mohammed Ababneh (ACT)

- Staggered and In-Line Submerged Liquid Jet Arrays for Power Electronics Using Variable Area Discharge Manifolds: Part I - Experimental (p123)** 410
Michael Henry, Kayla Reid, Sushil Bhavnani, Roy Knight, William D. Brannon (Auburn University);
John Maddox (University of Kentucky)
- Staggered and In-Line Submerged Liquid Jet Arrays for Power Electronics Using Variable Area Discharge Manifolds: Part II - Numerical (p192)** 417
Kayla Reid, Michael Henry, Roy Knight, Sushil Bhavnani (Auburn University);
John Maddox (University of Kentucky)
- Identification of the Dominant Heat Transfer Mechanisms during Confined Two-Phase Jet Impingement (p136)** 424
Matthew Clark, Justin Weibel, Suresh Garimella (Purdue University)

Session TI-6: Hot Spot Cooling and Jet Impingement II

Session Chairs: Mohammed Ababneh (ACT), Nicholas Haehn (Intel)

- Impingement Cooling Using a Variable-Diameter Synthetic Jet (p124)** 429
Alexander Zielinski, Monique Embury, Stephen Solovitz (Washington State University Vancouver)
- Flow Field Characteristics of Multiple Impinging Tapered Nozzles in Confined Channels for High Heat Flux Applications (p284)** 436
Prabhakar Subrahmanyam, Arun Krishnamoorthy (Intel); Jared Harvest (ANSYS)
- Measuring Heat Transfer Coefficients for Microchannel Jet Impingement Using Time-domain Thermoreflectance (p269)** 449
Thomas Germain, Tanvir Chowdhury, Jake Carter, Shawn Putnam (University of Central Florida)
- Numerical Investigation of Thermal Transport in Confined Single and Multiple Jet Impingements Through Porous Filled Non-uniform Cross Section Channels (p314)** 455
Carlos Zing, Shadi Mahjoob (California State University Northridge)

Session TI-7A: Thermal Interface Materials, Heat Spreaders, and Thermal Ground Planes

Session Chairs: Ridvan Sahan (Intel), Baris Dogruoz (Cisco)

- Combined Experimental-Numerical Investigation of Metal-Wax Interactions for Phase Change Thermal Energy Storage (p151)** 465
Prahlad Kulkarni, Prachi Kale, Collier Miers, Amy Marconnet (Purdue University)
- Investigation of Atomistic-scale Thin-Film Evaporation (p248)** 470
Kimia Montazeri, Shiwei Zhang, Mohammad Javad Abdolhosseini Qomi, Yoonjin Won
(University of California, Irvine)
- Highly Anisotropic Thermal Conductivity in Spin-Cast Polystyrene Nano-Films (p272)** 477
Joseph Katz, Michael Barako, Woosung Park, Aditya Sood, Mehdi Asheghi, Kenneth E. Goodson
(Stanford University)
- Synthesis of Thermal Compound and Its Application as a Thermal Interface Material of Power Module (p398)** 482
Seonja Song, Changkook Jang (Youngyiel Precision Co Ltd); Kyeongho Shin, Joohyung Kim (Inha University); Youngseok Kim (Hyundai Motor Company); Jaeuk Chu (Youngyiel Precision Co Ltd)

Session TI-7B: Air Cooling and Heat Exchangers

Session Chairs: Ashish Sinha (Chowbotics), Salih Erden (Istanbul Technical University)

- Two-phase Flow Simulations within Plate Heat Exchangers (p105)** 487
Raffaele Luca Amalfi, John Richard Thome (Ecole Polytechnique Federale de Lausanne)
- Experimental and Numerical Investigation of Liquid-to-Air Heat Exchangers (p154)** 497
Jaime Sanchez, Devdatta Kulkarni, Xudong Tang, Casey Winkel (Intel Corp)

| | |
|--|------------|
| Development of Hybrid Optimal Controller for Building AC Compressors (p286) | 504 |
| Matthew Blaser, Agustinus Lawandy, Bahman Abbasi (Oregon State University) | |
| A Numerical Study of Heat Transfer and Fluid Flow in a Channel with an Array of Pin Fins in Aligned and Staggered Configurations (p361) | 513 |
| Johnny Issa, Najib Saliba (University of Balamand); Amina El Cheikh (Lebanese American University) | |

Session TI-8A: Novel Air Cooling Devices and Systems

Session Chairs: Salih Erden (Istanbul Technical University), Ashish Sinha (Chowbotics)

| | |
|---|------------|
| Thermal and Exergy Analysis in UPS and Battery Rooms by Numerical Simulations (p355) | 521 |
| Carol Caceres (Villanova University); Alfonso Ortega (Santa Clara University); Luis Silva-Llanca (Universidad de la Serena); Gerard Jones (Villanova University); Nicholas Sapia (Verizon Wireless) | |
| Impact of Orifice Location on the Mechanical Response of Side and Central Orifice Synthetic Jets (p112) | 530 |
| Mohammad Zohaib Naseem, Polat Sendur, Mehmet Arik (Ozyegin University) | |
| Fluid Dynamics and Heat Transfer Generated by a Pair of Adjacent Impinging Synthetic Jets (p302) | 537 |
| Jean Paul D'Alencon, David Gallardo, Luis Silva-Llanca (Universidad de la Serena) | |
| An Investigation of Performance of Synthetic Jets Emanating from Circular, Elliptical and Rectangular Nozzles (p386) | 547 |
| Onuralp Isil (Ozyegin University), Baris Dogruoz (Cisco Systems), Mehmet Arik (Ozyegin University) | |

Session TI-8B: Characterization of Materials and Structures for Thermal Management of Electronics

Session Chairs: Baris Dogruoz (Cisco), Ridvan Sahan (Intel)

| | |
|--|------------|
| Thermal Management Technologies for Embedded Cooling Application (p292) | 556 |
| Andy Slippey, William Anderson, Michael Ellis, Clayton Hose, James Schmidt, Jens Weyant (ACT Inc) | |
| Rapid Thermal Characterization of Materials with Ultra-high Resolution of Droplet Size Specimens using the Three Omega Method (p392) | 562 |
| Corinna Grosse, Mohamad Abo Ras, Daniel May, Karim Elabshihy (Berliner Nanotest und Design GmbH); Kestutis Grigoras, Aapo Varpula, Mika Prunnila (VTT Technical Research Centre of Finland Ltd); Daniel May, Bernhard Wunderle (Chemnitz University of Technology) | |
| Thermal Conductance of Beta-Ga₂O₃/Metal Interfaces (p401) | 567 |
| Henry Aller, Xiaoxiao Yu, Andrew Gellman, Jonathan Malen, Alan McGaughey (Carnegie Mellon University) | |
| Uncertainty Quantification for a High Temperature Z-Meter Characterization System (p134) | 572 |
| Collier Miers, Amy Marconnet (Purdue University) | |

Session TI-9: Board-Level Liquid Cooling Solutions

Session Chairs: Anil Yuksel (IBM), Prabhakar Subrahmanyam (Intel)

| | |
|--|------------|
| Analytical Design Methodology for Liquid Based Cooling Solution for High TDP CPUs (p132) | 582 |
| Yuehong Fan, Casey Winkel, Devdatta Kulkarni, Wenbin Tian (Intel Corp) | |
| Design of a Two-Phase Gravity-Driven Micro-Scale Thermosyphon Cooling System for High-Performance Computing Data Centers (p177) | 587 |
| Andre Seuret, Arman Iranfar, Marina Zapater, John Richard Thome, David Atienza (Ecole Polytechnique Federale de Lausanne) | |
| Experimental Study of Two-Phase Cooling to Enable Large-Scale System Computing Performance (p200) | 596 |
| Devdatta Kulkarni, Xudong Tang, Sandeep Ahuja, Richard Dischler, Ravi Mahajan (Intel Corp) | |

Session TI-10: Boiling, Condensation, Evaporation, and Microgap Cooling I

Session Chairs: Mehmet Arik (Ozyegin University), Emil Rahim (Google)

| | |
|--|------------|
| Nanoelectrosprayed Liquid Jets for Evaporative Heat Transfer Enhancement (p114) | 602 |
| Joel Chapman, Peter Kottke, Andrei Fedorov (Georgia Institute of Technology) | |
| 3D Numerical Analysis of Phase Change Immersion Cooling for Electronic Components (p115) | 609 |
| Xudong An, Manish Arora, Wei Huang, William C. Brantley, Joseph Greathouse (Advanced Micro Devices) | |
| High Heat Flux Boiling Heat Transfer through Nanoporous Membranes (p164) | 615 |
| Qingyang Wang, Renkun Chen (University of California San Diego) | |
| Study on the Heat Transfer Mechanism in Nucleate Boiling of Water by Measuring Local Heat Flux and Temperature (p202) | 620 |
| Minchang Kim, Sung Jin Kim (KAIST) | |

Session TI-11: Boiling, Condensation, Evaporation, and Microgap Cooling II

Session Chairs: Emil Rahim (Google), Mehmet Arik (Ozyegin University)

| | |
|--|------------|
| Flow Boiling Heat Transfer of HFE7000 in Manifold Microchannels through Integrating Three-Dimensional Flow and Silicon Nanowires (p185) | 630 |
| Sheng Wang, Hsiu-Hung Chen, Chung-Lung Chen (University of Missouri Columbia) | |
| Physics of Thin Film Formation in Microchannels: New Physical Insights and Governing Correlations (p223) | 639 |
| Abdolreza Fazeli, Meisam Habibi Matin, Saeed Moghaddam (University of Florida) | |
| Two-Phase Thermosiphon Cooling using Integrated Heat Spreaders with Copper Microstructures (p216) | 645 |
| Vasco Abreu, Matthew Harrison, Joshua Gess, Ana S. Moita (Oregon State University) | |

Session TI-12A: Single/Two-Phase Flow in Microchannels and Cold Plates

Session Chairs: Prabhakar Subrahmanyam (Intel), Anil Yuksel (IBM)

| | |
|--|------------|
| Maldistribution of Two-Phase Flow in Parallel Channel Heat Sinks: Effects of Thermal Connection between Channels (p128) | 653 |
| Gaurav Patankar, Todd Salamon (Nokia Bell Labs) | |
| Experimental Characterization of Cold Plates used in Cooling Multi Chip Server Modules (MCM) (p227) | 664 |
| Bharath Ramakrishnan, Yaser Hadad, Sami Alkharabsheh, Paul Chiarot, Kanad Ghose, Bahgat Sammakia (SUNY Binghamton); Vadim Gektin (Futurewei Technologies); Wang Chao (Huawei Technologies) | |
| Geometric Optimization of an Impinging Cold-Plate with a Trapezoidal Groove Used for Warm Water Cooling (p229) | 673 |
| Yaser Hadad, Reza Pejman, Bharath Ramakrishnan, Paul Chiarot, Bahgat Sammakia (SUNY Binghamton) | |
| Flow Analysis and Linearization of Rectangular Butterfly Valve Flow Control Device for Liquid Cooling (p359) | 683 |
| Rajesh Kasukurthy, Pencala Sumanth Challa, Rishi Ruben Palanikumar, Barath Ragul Manimaran, Dereje Agonafer (University of Texas at Arlington) | |

Session TI-12B: Thermoelectricity, TEC, and Peltier Devices

Session Chairs: Amy Xia (Intel), Mark North (Thermacore)

| | |
|--|------------|
| Transient Heat Transfer Analysis of Thermo-Electric Cooler Thermal Tools (p153) | 688 |
| Jaime Sanchez (Intel Corp) | |
| Packaging and Thermal Decoupling of an Optical Array using a Thermoelectric Cooler (p279) | 695 |
| Sevket Umut Yuruker, Raphael Mandel, Daniel Bae, Michael Ohadi (University of Maryland), Vadim Gektin (Futurewei Technologies) | |

| | |
|--|------------|
| Thermoelectric Cooling Device Based on Holey Silicon (p196) | 701 |
| Zongqing Ren, Jaeho Lee (University of California Irvine) | |

TRACK: THERMAL II – SYSTEM LEVEL

Session TII-1: Data Center Energy Efficiency I

Session Chairs: Ali Akbar Merrikh (Qualcomm), Ali Kalantarian (Advanced Micro Devices)

| | |
|--|------------|
| A Compact Cooling-System Model for Transient Data Center Simulations (p157) | 707 |
| James VanGilder, Christopher Healey, Michael Condor, Wei Tian, Quentin Menusier (Schneider Electric) | |
| Data Driven Prediction Model (DDPM) for Server Inlet Temperature Prediction in Raised-Floor Data Centers (p184) | 716 |
| Raymond Lloyd (IBM Research Ireland); Marek Rebow (Dublin Institute of Technology) | |
| Modeled and Experimentally Validated Retrofit of High Consumption Data Centers on an Academic Campus (p189) | 726 |
| Fabio Battaglia, Raja Maheedhara, Amar Krishna, Farah Singer, Michael Ohadi (University of Maryland) | |

Session TII-2: Data Center Energy Efficiency II

Session Chairs: Ajay Vadakkepatt (Qualcomm), Rajat Mittal (Oculus)

| | |
|--|------------|
| Algorithm for Simultaneous Optimization of an Array of Heat Sinks (p225) | 734 |
| Georgios Karamanis, Marc Hodes (Tufts University) | |
| A Test Study of Technology Cooling Loop in a Liquid Cooling System (p246) | 740 |
| Tianyi Gao, Hu Tang, Yan Cui, Zhiming Luo (Baidu) | |
| An Experimental Analysis of Hot Aisle Containment Systems (p259) | 748 |
| Sadegh Khalili, Anuroop Desu, Bahgat Sammakia, Kanad Ghose (Binghamton University); Husam Alissa (Microsoft) | |
| Exploration of a Hybrid Analytical Thermal Topology Optimization Method for an Additively Manufactured Heat Sink (p379) | 761 |
| H. Peter de Bock (GE Global Research) | |

Session TII-3: LEDs and Photovoltaics

Session Chairs: Ashish Gupta (Intel), Vibhash Jha (NXP Semiconductors), Vikram Manthri (Amazon)

| | |
|---|------------|
| Experimental Determination of Junction-to-Case Thermal Resistance in LED Compact Thermal Models (p171) | 768 |
| Tomasz Torzewicz, Marcin Janicki, Andrzej Napieralski (Lodz University of Technology) | |
| A Comparative Study of Reflective and Transmissive Phosphor-Converted Laser-Based White Lighting (p186) | 773 |
| Yupu Ma, Xiaobing Luo (Huazhong University of Science and Technology) | |
| Design Considerations Based on the Effects of Varying Temperature Conditions on the Efficiency of Size Constrained Electronic Power Supplies for CubeSat Applications (p232) | 778 |
| Rachid Darbali-Zamora, Nicolas Cobo-Yepes, Eduardo Ortiz-Rivera (University of Puerto Rico Mayaguez) | |
| Optimization of an Organic Rankine Cycle through a Control Strategy for Waste Heat Recovery (p300) | 788 |
| Luis Silva-Llanca, Carolina Ponce, Manuel Araya (Universidad de la Serena); Andres J. Diaz (Universidad Diego Portales) | |

Session TII-4: Power Electronics

Session Chairs: Taravat Khadivi (Qualcomm), Ali Akbar Merrikh (Qualcomm)

| | |
|--|------------|
| Waste Heat Recovery from Distributed Rack-based Fuel Cells using Thermoelectric Generators (p145) | 795 |
| Khosrow Ebrahimi (Boise State University); Alfonso Ortega (Santa Clara University); Calvin Li (Villanova University); Kazuaki Yazawa (Purdue University); Sean James (Microsoft) | |

| | |
|--|------------|
| (paper withdrawn) | 815 |
| Co-Designed High Voltage Module (p310) | 824 |
| Lauren Boteler, Miguel Hinojosa (US Army Research Laboratory); Steven Miner (US Naval Academy) | |
| Electrical and Thermal Analysis of Vertical GaN-on-GaN PN Diodes (p311) | 831 |
| Luke Yates, Georges Pavlidis, Samuel Graham (Georgia Institute of Technology); Shigeyosi Usami, Kentaro Nagamatsu, Yoshio Honda; Hiroshi Amano (Nagoya University) | |

Session TII-5: Immersion Cooling and Refrigeration

Session Chairs: Andrew McNamara (Advanced Micro Devices), Vivek Sahu (Apple), Ajay Vadakkepatt (Qualcomm)

| | |
|---|------------|
| Hydrodynamic Patterns of a Droplet Train Impinging onto Superheated Nanotube Surfaces (p162) | 838 |
| Wei Tong, Zhen Qin, Fei Duan (Nanyang Technological University) | |
| Analysis and Active Control of Pressure Drop Oscillation in Microchannel Vapor Compression Cycle (p226) | 842 |
| Jin Qi, John Wen, Shankar Narayanan (Rensselaer Polytechnic Institute) | |
| Organic Rankine Cycle as Waste Heat Recovery System in Data Centers: Design and Construction of a Prototype (p250) | 850 |
| Sebastian Araya, Gerard Jones, Amy Fleischer (Villanova University) | |

Session TII-6: Data Center and Energy Efficiency III

Session Chairs: Ajit Vallabhaneni (Qualcomm), Mehdi Saeidi (Qualcomm)

| | |
|--|------------|
| An Advanced Data Center Multi-Chiller Dynamic Load Distribution Methodology and Engineering Practice (p205) | 859 |
| Yiming Luo, Jianchao Cao, Biao Li, Yahui Zhao, Tangbo Jing, Lifei Zhang (Baidu); Nishi Ahuja, Jun Zhang, Yuyang Xia, Xiang Zhou (Intel Corp) | |
| Transient Data Center Temperatures after a Primary Power Outage (p283) | 865 |
| Christopher Healey, James VanGilder, Michael Condor, Wei Tian (Schneider Electric) | |
| Artificial Neural Network Based Prediction of Temperature and Flow Profile in Data Centers (p288) | 871 |
| Jayati Athavale, Yogendra Joshi, Minami Yoda (Georgia Institute of Technology) | |
| Thermoelectric On-Spot Energy Harvesting for Diagnostics of Water Service Pipelines (p183) | 881 |
| Kazuaki Yazawa (Purdue University), Katsuhiko Tanaka, Takashi Yajima (Tokyo Electric Power Company) | |

Session TII-8: Space, Aerospace, and Telecommunications

Session Chairs: Shima Hajimirza (Texas A&M University), Andrew Poynot (Signature Science, LLC)

| | |
|--|------------|
| Transient Electro-Thermal Coupled System Simulation - Modeling Approach and Experimental Validation (p109) | 889 |
| Ralph Schacht (Brandenburg Technology University); Sven Rzepka (Fraunhofer Institute ENAS) | |
| A Novel Networking Box System Architecture and Design for Data Center Energy Efficiency (p187) | 897 |
| Chuansheng Cheng, Hua Chen, Biquan Liang, Ning Liu, Chao Liu (Baidu); Jun Zhang, Nishi Ahuja, Jialiang Xu, Xiang Zhou (Intel) | |
| Thermal Interface Material Enablement of Off-Board Two-Phase Cooling (p220) | 905 |
| Matthew Smith (Georgia Institute of Technology); Raffaele Amalfi (Ecole Polytechnique Federale de Lausanne); Todd Salamon (Nokia Bell Labs); John Thome (Ecole Polytechnique Federale de Lausanne) | |
| Porous Nickel as a Selective Emitter for Surface Cooling in Various Environments (p274) | 915 |
| Jonathan Sullivan, Anirudh Krishna, Jaeho Lee (University of California Irvine) | |

Session TII-9: Automotive, Batteries, and Thermal Storage

Session Chairs: Aydin Nabovati (Tesla), Man Prakash Gupta (Ford)

| | |
|---|------------|
| Thermal Management within Multi-Disciplinary System Design of a Rubik's-Cube-sized 2kW Power Inverter (p362) | 921 |
| David Guirguis, Miad Nasr, Samantha Murray, Hirokazu Matsumoto, Olivier Trescases, Cristina Amon (University of Toronto) | |
| Experimental Validation of Thermal Performance of a Plate Heat Exchanger (PHX) with Phase Change Materials (PCM) for Thermal Energy Storage (TES) (p141) | 927 |
| Navin Kumar, Reynaldo Chavez, Debjyoti Banerjee (Texas A&M University) | |
| Thermal Management Strategies for a High-Frequency, Bi-Directional, On-Board Electric Vehicle Charger (p344) | 935 |
| Kshitij Gupta, Carlos Da Silva, Miad Nasr, Amir Assadi, Hirokazu Matsumoto, Olivier Trescases, Cristina Amon (University of Toronto) | |

Session TII-10: Data Center Energy Efficiency IV

Session Chairs: Prabhakar Marepalli (Intel), Mehdi Saeidi (Qualcomm)

| | |
|---|------------|
| The Impact of Cold Aisle Containment Pressure Relief on IT Availability (p324) | 944 |
| Mohammad Tradat, Udaya Puvvadi, Bahgat Sammakia, Kanad Ghose (SUNY Binghamton); Mahmoud Ibrahim, Andrew Calder, Thomas Peddle (Panduit); Mark Seymour (Future Facilities); Husam Alissa (Microsoft) | |
| Impact of Static Pressure Differential between Supply Air and Return Exhaust on Server Level Performance (p356) | 953 |
| Ashwin Siddarth, Richard Eiland, John Fernandes, Dereje Agonafer (University of Texas at Arlington) | |
| CFD Simulation and Optimization of the Cooling of Open Compute Machine Learning "Big Sur" Server (p357) | 962 |
| Mangesh Dhadve, Jimil Shah, Dereje Agonafer (University of Texas at Arlington) | |
| Experimental Characterization of Vertically Split Distribution Wet-Cooling Media used in the Direct Evaporative Cooling of Data Centers (p377) | 971 |
| Ahmed Al Khazraji, Ashwin Siddarth, Mullaivendhan Varadharasan, Dereje Agonafer (University of Texas at Arlington); Abhishek Guhe, James Hoverson, Mike Kaler (Mestek Inc) | |

Session TII-11: Mobile, Internet of Things I

Session Chairs: Krishna Valavala (Intel), Youmin Yu (Qualcomm)

| | |
|--|------------|
| Thermal Challenges and Solutions of M.2 Solid State Drive (p129) | 979 |
| Ning Ye, Dmitry Vaysman, In-Soo Yoon, Hem Takiar (Western Digital); Yangming Liu, Zhongli Ji (SanDisk) | |
| A System-Level Thermal Simulator with Automatic Meshing Techniques (p180) | 984 |
| Jui-Hung Wang, Yu-Min Lee, Hsuan-Hsuan Hsiao (National Chiao Tung University); Liang-Chia Cheng (Industrial Technology Research Institute) | |
| Designing a Temperature Model to Understand the Thermal Challenges of Portable Computing Platforms (p118) | 992 |
| Ying-Ju Yu, Carole-Jean Wu (Arizona State University) | |

Session TII-12: Mobile, Internet of Things II

Session Chairs: Youmin Yu (Qualcomm), Krishna Valavala (Intel)

| | |
|--|-------------|
| Optimization of TEG for Human Body Powered Mobile Devices (p263) | 1000 |
| Jiahui Cao (University of California, Irvine) | |
| Transient Thermal Analysis for M.2 SSD Thermal Throttling: Detailed CFD Model vs. Network-Based Model (p130) | 1009 |
| Hedan Zhang, Shay Braha, Ernold Thompson, Ning Ye, Nir Amir (Western Digital); Hainan Wang, Nathan Ai, C. T. Kao (Cadence) | |

| | |
|--|-------------|
| Impact of Chipset Configuration on Thermal Performance in Smartphones (p247) | 1015 |
| Youmin Yu, Nader Nikfar, Todd Sutton (Qualcomm) | |
| Fast Prediction of Thermal Throttling Design in M.2 Solid State Drive (p131) | 1022 |
| Yangming Liu, Ernold Thompson (SanDisk); Ning Ye, Dmitry Vaysman, In-Soo Yoon, Hem Takiar (Western Digital) | |

TRACK: MECHANICS AND RELIABILITY

Session M-1: Applied Reliability and Failure Analysis

Session Chairs: Tuhin Sinha (IBM), Kritika Upreti (Intel)

| | |
|---|-------------|
| Flexible Power-Source Survivability Assurance under Bending Loads and Operating Temperatures Representative of Stresses of Daily Motion (p304) | 1027 |
| Pradeep Lall, Amrit Abrol, Ben Leever, Jason Marsh (Auburn University) | |
| Reliability Evaluation of BGA Solder Joints in Vision Processor by Passive Cooling (p172) | 1035 |
| Kaito Uehata, Ryosuke Yano, Qiang Yu (Yokohama National University) | |
| Effect of Green EMCs on Fatigue Reliability of Molded Cu Wirebond System (p325) | 1041 |
| Pradeep Lall, Shantanu Deshpande, Nakul Kothari (Auburn University); Luu Nguyen (Texas Instruments) | |

Session M-2: Advanced Methodologies for Reliability

Session Chairs: Przemyslaw Gromala (Robert Bosch GmbH), Jin Yang (Intel)

| | |
|---|-------------|
| Damage Evolution in MEMS Pressure Sensors during High Temperature Operating Life and Prolonged Storage at Sub-Zero Temperature (p318) | 1050 |
| Pradeep Lall, Amrit Abrol (Auburn University); David Locker, Bruce Hughes (US Army AMRDEC) | |
| Evaluation of Aging Induced Microstructural Evolution in Lead Free Solders Using Scanning Probe Microscopy (p337) | 1062 |
| Sudan Ahmed, Jeffrey Suhling, Pradeep Lall (Auburn University) | |
| A Novel Concept for Accelerated Stress Testing of Thermal Greases and In-situ Observation of Thermal Contact Degradation (p170) | 1071 |
| Bernhard Wunderle, Daniel May, Jens Heilmann, Joerg Arnold, Josef Hirscheider, Y. Li (Chemnitz University of Technology); Joerg Bauer (Fraunhofer IZM); Mohamad Abo Ras (Berliner Nanotest and Design GmbH) | |
| Mechanical Characterization of Intermetallic Compounds in SAC Solder Joints at Elevated Temperatures (p346) | 1081 |
| Abdullah Fahim, Sudan Ahmed, Jeffrey Suhling, Pradeep Lall (Auburn University) | |

Session M-3: Mechanics in Assembly and Packaging I

Session Chairs: Bernhard Wunderle (Chemnitz University of Technology),
Vibhash Jha (NXP Semiconductors), Sami Alkharabsheh (Ford)

| | |
|--|-------------|
| Strength Analysis of Resin Delamination of Packaging Structure of Power Module (p176) | 1091 |
| Sho Teradaira, Yukichi Furuyama, Qiang Yu (Yokohama National University) | |
| Measurement and Prediction of Interface Crack Growth at the PCB-Epoxy Interfaces under High-G Mechanical Shock (p320) | 1097 |
| Pradeep Lall, Kalyan Dornala (Auburn University); John Deep (US AFRL); Ryan Lowe (ARA Associates) | |
| Reaction Kinetics and Rheological Model Coefficient Extraction for Epoxy Mold Compounds (p251) | 1106 |
| A. R. Nazmus Sakib, Vibhash Jha, Amar Mavinkurve, Sheila Chopin (NXP Semiconductors) | |
| Moisture-Induced Die Stresses in PBGA Packages Exposed to Various Environments (p340) | 1112 |
| Jun Chen, Quang Nguyen, Jordan Roberts, Jeffrey Suhling, Richard Jaeger, Pradeep Lall (Auburn University) | |

Session M-4: Mechanics in Assembly and Packaging II

Session Chairs: Bernhard Wunderle (Chemnitz University of Technology),
Vibhash Jha (NXP Semiconductors), Sami Alkharabsheh (FordC)

| | |
|---|------|
| Development of Test Protocols for the Flexible Substrates in Wearable Applications (p305) | 1120 |
| Pradeep Lall, Jinesh Narangaparambil, Amrit Abrol (Auburn University); Ben Leever (USAF Research Labs); Jason Marsh (NextFlex Manufacturing Institute) | |
| Mechanical Response of Assemblies Bonded with Double-Layered Pressure-Sensitive Adhesives (PSAs) (p315) | 1128 |
| Hao Huang, Abhijit Dasgupta (University of Maryland); Ehsan Mirbagheri, Krishna Darbha (Microsoft) | |
| Mechanical Characterization of Solder Mask Materials (p342) | 1133 |
| Promod Chowdhury, Jeffrey Suhling, Pradeep Lall (Auburn University) | |
| Simulation Improved Testing of Fan-out Packaging (p282) | 1142 |
| Chun-Wei Hsiao, Mei-Ling Wu (National Sun Yat-Sen University); Shang Lee, Shiny Huang, Chiyu Wang, Brain Wu (Advanced Semiconductor Engineering Inc.) | |

Session M-5: Modeling and Analytical Methods for Mechanics and Reliability of Electronics Packaging I

Session Chairs: Shidong Li (IBM), Meriem Akin (IMPT)

| | |
|--|------|
| Improved Submodeling Finite Element Simulation Strategies for BGA Packages Subjected to Thermal Cycling (p339) | 1146 |
| Chienchih Chen, Jeffrey Suhling, Pradeep Lall (Auburn University) | |
| Meshless Computational Tools for Damage and Failure Modeling (p293) | 1155 |
| Srujan Rokkam, Quang Truong (Advanced Cooling Technologies); Max Gunzburger (Florida State University) | |
| Analysis of Progressive Damage in Fuze Electronics using Micro-Computed Tomography and Finite Element Models (p323) | 1160 |
| Pradeep Lall, Nakul Kothari (Auburn University); John Deep (US AFRL); Ryan Lowe (ARA Associates) | |

Session M-6: Modeling and Analytical Methods for Mechanics and Reliability of Electronics Packaging II

Session Chairs: Shidong Li (IBM), Meriem Akin (IMPT)

| | |
|---|------|
| Fatigue Life Predictive Model and Acceleration Factor Development for Decoupling Capacitors (p241) | 1169 |
| Krishna Tunga, Joseph Ross, Kamal Sikka, Thomas Lombardi, Bakul Parikh, Eric Turcotte, Catherine Dufort, David Turnbull (IBM Corp) | |
| A Novel Numerical Multiphysics Framework for the Modeling of Cu-Al Wire Bond Corrosion under HAST Conditions (p330) | 1177 |
| Pradeep Lall, Yihua Luo (Auburn University); Luu Nguyen (Texas Instruments) | |
| Development of a Computational Modeling and Experimental Validation Approach for KSF LED Packages in a 65" Ultra-Thin LED TV System (p265) | 1186 |
| Metehan Elibol, Mustafa Caglar Ozaydin (Vestel Electronics); Mehmet Arik (Ozyegin University) | |
| Comparison of FEA Modeling Techniques for Plastic Ball Grid Array Assemblies (p395) | 1195 |
| Chienchih Chen, Jeffrey Suhling, Pradeep Lall (Auburn University) | |

Session M-7: Solder Joint Reliability I

Session Chairs: Chandradip Patel (Schlumberger), Quang Nguyen (Micron)

| | |
|--|------|
| The Influence of Poisson's Ratio on the Reliability of SAC Lead Free Solder Joints (p349) | 1207 |
| KM Rafidh Hassan, Jeffrey Suhling, Pradeep Lall (Auburn University) | |

| | |
|---|------|
| (paper withdrawn) | 1217 |
| SMT/PTH Solder Joint Reliability under Extreme Cold Thermal Cycles (p150) | 1224 |
| Reza Ghaffarian (Jet Propulsion Laboratory) | |
| Investigation of Microstructural Evolution in SAC Solders Exposed to Short-Term and Long-Term Aging (p352) | 1234 |
| Jing Wu, Jeffrey Suhling, Pradeep Lall (Auburn University) | |

Session M-8: Solder Joint Reliability II

Session Chairs: Chandradip Patel (Schlumberger), Cong Zhao (Apple)

| | |
|--|------|
| Fatigue Properties of Lead-Free Doped Solder Joints (p253) | 1243 |
| Sinan Su, Francy Akkara, Mohammed Abueed, Minghong Jian, Sa'd Hamasha, Jeffrey Suhling, Pradeep Lall (Auburn University) | |
| Life Expectancies of Ni-doped SAC Solder Alloy Subjected to Drop Test Loading (p280) | 1249 |
| Jia-Shen Lan, Mei-Ling Wu (National Sun Yat-Sen University) | |
| Reliability of SAC Leadfree Solders in Automotive Underhood Temperature-Vibration (p329) | 1255 |
| Pradeep Lall, Vikas Yadav, Di Zhang, Jeff Suhling (Auburn University) | |

Session M-9: Solder Characterization and Modeling I

Session Chairs: Krishna Tunga (IBM), Sandeep Shantaram (NXP Semiconductors)

| | |
|--|------|
| Feature Extraction and RUL Prediction of SAC Solder Alloy Packages by Different Statistical and Time-Frequency Analysis Techniques under Simultaneous Temperature-Vibration Loads (p327) .. | 1270 |
| Pradeep Lall, Tony Thomas, Jeff Suhling (Auburn University) | |
| Temperature-Dependent Electrical and Thermal Conductivity of Glassy Carbon Wires (p148) | 1280 |
| Laia Ferrer-Argemi, Albert Cisquella-Serra, Marc Madou, Jaeho Lee (University of California, Irvine) | |
| Board Level Solder Joint Reliability Assessment Study of Megtron 6 vs. FR-4 under Power Cycling and Thermal Cycling (p312) | 1289 |
| Jyotirmoy Denria, Pavan Rajmane, Dereje Agonafer (University of Texas at Arlington) | |

Session M-10: Solder Characterization and Modeling II

Session Chairs: Krishna Tunga (IBM), Sa'd Hamasha (Auburn)

| | |
|--|------|
| Effect of Prolonged Storage on High Strain Rate Mechanical Properties of SAC-Q Leadfree Solder at High Operating Temperature (p328) | 1296 |
| Pradeep Lall, Vikas Yadav, Jeff Suhling (Auburn University); David Locker (US Army AMRDEC) | |
| A Joint-Scale Test Specimen for Tensile Properties of Solder Alloys (p267) | 1309 |
| Abhishek Deshpande, Qian Jiang, Abhijit Dasgupta (University of Maryland) | |
| A Comparative Study of the High Temperature Mechanical Behavior of Lead Free Solders (p338) ... | 1314 |
| Mohammad Alam, Jeffrey Suhling, Pradeep Lall (Auburn University) | |
| Effects of Mechanical Cycling on the Microstructure of SAC305 Lead Free Solder (p397) | 1324 |
| Md Mahmudur Chowdhury, Nianjun Fu, Mohd Aminul Hoque, Sudan Ahmed. Jeffrey Suhling, Sa'd Hamasha, Pradeep Lall (Auburn University) | |

Session M-11: Thermal-Mechanical Interactions in Microelectronics Packages and Systems I

Session Chairs: Vibhash Jha (NXP Semiconductors), Jaeho Lee (UC Irvine), Yingying Wang (Qualcomm)

| | |
|---|------|
| Thermal Expansion Investigation of Liquid Cold Plate with Varying Ambient Temperature at Storage (p108) | 1333 |
| Murat Parlak (Aselsan, Inc, University of Gazi-Ankara); Vedat Yagci (Aselsan, Inc, Middle East Technical University-Ankara) | |

| | |
|---|-------------|
| A Study on Die Stresses in Flip Chip Packages Subjected to Various Hygrothermal Exposures (p399) | 1339 |
| Quang Nguyen, Jordan Roberts, Jeffrey Suhling, Richard Jaeger, Pradeep Lall (Auburn University) | |
| Thermal Performance Evaluation and Reliability Analysis of Air-Cooled Power Modules (p173) | 1351 |
| Koichi Ishiyama, Shingo Nakayama, Qiang Yu (Yokohama National University) | |
| Effect of Thermal Cycling on Reliability of QFN Packages (p326) | 1357 |
| Pradeep Lall, Shantanu Deshpande, Nakul Kothari (Auburn University); Luu Nguyen (Texas Instruments) | |

Session M-12: Thermal-Mechanical Interactions in Microelectronics Packages and Systems II

Session Chairs: Vibhash Jha (NXP Semiconductors), Jaeho Lee (UC Irvine), Yingying Wang (Qualcomm)

| | |
|--|-------------|
| Simulation Driven Design of Novel Integrated Circuits - Part 4: Method of Validation of Coupled Thermal and Thermo-Mechanical Simulation (p276) | 1366 |
| Przemyslaw Gromala, Alicja Palczynska (Rosbert Bosch GmbH); Bulong Wu, Bongtae Han (University of Maryland) | |
| Effect of Solder Sphere Alloys and Surface Finishes on the Reliability of Lead-Free Solder Joints in Accelerated Thermal Cycling (p258) | 1374 |
| Francy John Akkara, Cong Zhao, Raed Alathamneh, Sinan Su, Mohammed Abueed, Sa'd Hamasha, Jeff Suhling, Pradeep Lall (Auburn University) | |
| Coupled Thermal and Thermo-Mechanical Simulation for Flip-Chip Component Level Copper Pillar Bump Fatigue (p255) | 1381 |
| Sandeep Shantaram, A. R. Nazmus Sakib, Nishant Lakhera (NXP Semiconductors) | |
| Evolution of the Cyclic Stress-Strain and Constitutive Behaviors of Doped Lead Free Solders During Fatigue Testing (p396) | 1387 |
| Mohd Aminul Hoque, Md Mahmudur Chowdhury, Nianjun Fu, Jeffrey Suhling, Sa'd Hamasha, Pradeep Lall (Auburn University) | |

2018 Richard Chu ITherm Award for Excellence Presentation

| | |
|--|-------------|
| The Heat Conduction Renaissance | 1396 |
| Aditya Sood, Eric Pop, Mehdi Asheghi, and Kenneth E. Goodson (Stanford University) | |